



**POLITECNICO
MILANO 1863**

DIPARTIMENTO DI
INGEGNERIA GESTIONALE

LATIN AMERICA

CHILE – SANTIAGO DE CHILE

UNIVERSIDAD DE CHILE

University Code: CHL SANTIAGO4

slots for Management Engineering: (@Faculty of Physical and Mathematical Sciences)

Semester Exchange: 4 students for each AY (shared with other CS)

Level: MSc

Academic Year:

March – July (Fall Semester)

August – December (Spring Semester)

Please view further details about the Academic Calendar [here](#)

Grading scale: From 1 to 7, being 7 the best score. The minimum grade to pass is 4. 7.0 – Superior Achievement; 6.5 – Excellent; 6 – Very Good; 5.5/5.0/4.5 – Good; 4.0 – Fair/Passing Grade (P); 3.9-1.0 – Failure (F).

Recommended for the following Polimi MSc Majors: Industrial Management; Supply Chain Management; Analytics for Business; Digital Business Innovation; Complex Projects Business; International Business.

NB: As for the English taught courses, it says "se dicta en inglés" in the details of the courses. Courses are held mainly in the autumn semester (March - July). Students can access courses also from other Master of Science Programmes within the **Faculty of Physical and Mathematical Sciences**.

Language Proficiency Requirements: A level of command of Spanish adequate for academic work, certifiable with level B1 in the Diploma of Spanish as a Foreign Language (DELE) from Instituto Cervantes or equivalent.

RANKING:

QS University Rankings #183

QS World University Ranking by Subject (Engineering and Technology) #175

QS Latin America University Rankings #3

Useful Link

[Link to University website](#)

[Link to further useful info for exchange students](#)

[Course information for exchange students](#)

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